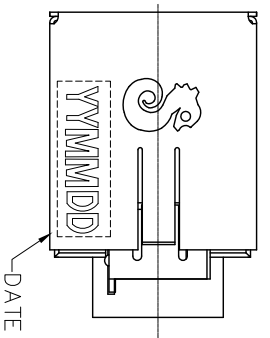
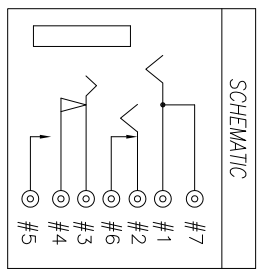
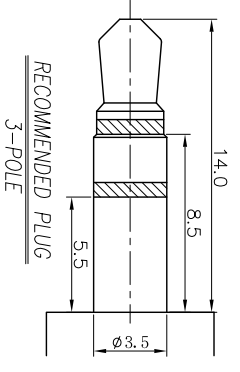


RECOMMENDED PCB LAYOUT (TOP VIEW)
(TOLERANCE: ±0.05)



- SPECIFICATIONS:
- INSULATION RESISTANCE BETWEEN ANY ADJACENT OPEN CIRCUIT TERMINAL SHELL NOT BE LESS THAN 100MΩ MEASURED BY 500 VDC MEGGER.
 - CONTACT RESISTANCE: 30mΩ MAX.
 - INSULATION VOLTAGE WITHSTAND: 500V AC FOR ONE MINUTE.
 - UNLESS OTHERWISE SPECIFIED, TEST IS TO BE MADE AT 5-35°C IN TEMPERATURE AND 45-85% IN HUMIDITY. BUT, IF ANY VAGUE DATA IS OCCURED ON TEST RESULT, ANOTHER TEST SHALL BE MADE AT 20°C±2°C IN TEMP., 60-70% IN HUMIDITY.
 - LIFE TEST: 5,000 CYCLES MIN. (NON-LOAD)
 - INSERTION FORCE: 0.4 - 3kg.
 - WITHDRAWAL FORCE: 0.3 - 2kg.
 - AFTER LIFE TEST, CONTACT RESISTANCE: 50mΩ MAX.
 - AFTER HUMIDITY TEST, INSULATION RESISTANCE: 50MΩ MIN.
 - MARKING: MARK "☉" ON TOP OF CONNECTOR.
 - PACKAGING: TAPE & REEL.
 - TO CONFORM TO SINGATRON HAZARDOUS SUBSTANCE FREE SPEC.
 - GREEN PRODUCT IDENTIFICATION MARK ON JACK
 - GREEN PRODUCT IDENTIFICATION LABEL ON PACKAGING: **GR PAAS**
 - SOLDER HEAT RESISTANCE: 260°C 10 SECS.

REV.	ECN NO.	OR DESCRIPTION	REVISED	DATE
B	ECN:S070111		YUNYA	2007.1.30
C	ECN:S071106	▲	BRUCE	2007.11.14
D	ECN NO:S110320		Cerry	2011.03.28

H	SHIELDING	1	PHOSPHOR BRONZE 0.2t	Ni 60u" Min.
G	TRANSFER TERMINAL	1	PHOSPHOR BRONZE 0.2t	GOLD FLASH ON CONTACT AREA
F	BREAK TERMINAL	1	PHOSPHOR BRONZE 0.2t	Sn 120u" ON SOLDER
E	RING SPRING	1	PHOSPHOR BRONZE 0.2t	ALL OVER Ni 50u"
D	SHUNT TERMINAL-A	1	BRASS 0.25t	
C	TIP SPRING	1	PHOSPHOR BRONZE 0.25t	Ag 20u" Min OVER Ni 60u" Min.
B	EARTH	1	COPPER ALLOY 0.3t	
A	BODY	1	HIGH TEMP.THERMOPLASTIC UL 94V-0	BLACK
NO	DESCRIPTION	QTY	MATERIAL	PLATING & COLOR
<p>UNLESS OTHERWISE SPECIFIED TOLERANCES</p> Singatron Enterprise Co., Ltd. 信音企業股份有限公司 3.5φ PHONE JACK TITLE DWN <i>gany</i> PART NO. 2S1-S351-015 CHKD <i>LISSBN</i> SCALE: 4/1 UNIT: mm APVD <i>lonny</i> SIZE: A3 SHEET: 1 OF 1 REV: D CUSTOMER COPY				
DECIMALS:	ANGLES:			
X : ±0.5	X : ±2°			
X.X : ±0.3	X.X : ±1'			
X.XX : ±0.2				